

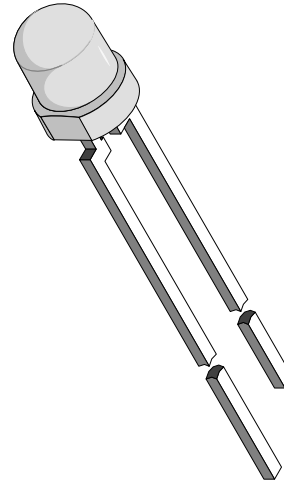
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### GaAs Infrared Emitting Diode in $\varnothing$ 3 mm (T-1) Package

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#### Description

TSUS 4300 is an infrared emitting diode in standard GaAs on GaAs technology, molded in a clear, blue tinted plastic package. Its lens provides a high radiant intensity without external optics.



94 8636

#### Features

- High radiant power and radiant intensity
- Low forward voltage
- Suitable for DC and high pulse current operation
- Standard T-1( $\varnothing$  3 mm) package
- Package flattening as additional polarity sign
- Angle of half intensity  $\varphi = \pm 16^\circ$
- Peak wavelength  $\lambda_p = 950$  nm
- High reliability
- Good spectral matching to Si photodetectors

#### Applications

Infrared remote control systems with small package and low cost requirements in combination with silicon photo detectors.

Infrared source in reflective sensors, tape end detection.

Excellent matching with phototransistor TEFT 4300.

## Absolute Maximum Ratings

 $T_{amb} = 25^{\circ}\text{C}$ 

Parameter	Test Conditions	Symbol	Value	Unit
Reverse Voltage		$V_R$	5	V
Forward Current		$I_F$	100	mA
Peak Forward Current	$t_p/T=0.5, t_p=100\ \mu\text{s}$	$I_{FM}$	200	mA
Surge Forward Current	$t_p=100\ \mu\text{s}$	$I_{FSM}$	2	A
Power Dissipation		$P_V$	170	mW
Junction Temperature		$T_j$	100	$^{\circ}\text{C}$
Operating Temperature Range		$T_{amb}$	-55...+100	$^{\circ}\text{C}$
Storage Temperature Range		$T_{stg}$	-55...+100	$^{\circ}\text{C}$
Soldering Temperature	$t \leq 5\text{sec}, 2\ \text{mm from case}$	$T_{sd}$	260	$^{\circ}\text{C}$
Thermal Resistance Junction/Ambient		$R_{thJA}$	450	K/W

## Basic Characteristics

 $T_{amb} = 25^{\circ}\text{C}$ 

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
Forward Voltage	$I_F = 100\ \text{mA}, t_p = 20\ \text{ms}$	$V_F$		1.3	1.7	V
Forward Voltage	$I_F = 1.5\ \text{A}, t_p = 100\ \mu\text{s}$	$V_F$		2.2		V
Temp. Coefficient of $V_F$	$I_F = 100\text{mA}$	$TK_{VF}$		-1.3		mV/K
Reverse Current	$V_R = 5\ \text{V}$	$I_R$			100	$\mu\text{A}$
Breakdown Voltage	$I_R = 100\ \mu\text{A}$	$V_{(BR)}$	5	40		
Junction Capacitance	$V_R = 0\ \text{V}, f = 1\ \text{MHz}, E = 0$	$C_j$		30		pF
Radiant Intensity	$I_F = 100\ \text{mA}, t_p = 20\ \text{ms}$	$I_e$	7	18		mW/sr
Radiant Intensity	$I_F = 1.5\ \text{A}, t_p = 100\ \mu\text{s}$	$I_e$		160		mW/sr
Radiant Power	$I_F = 100\ \text{mA}, t_p = 20\ \text{ms}$	$\phi_e$		13		mW
Temp. Coefficient of $\phi_e$	$I_F = 20\ \text{mA}$	$TK_{\phi_e}$		-0.8		%/K
Angle of Half Intensity		$\varphi$		$\pm 16$		deg
Peak Wavelength	$I_F = 100\ \text{mA}$	$\lambda_p$		950		nm
Spectral Bandwidth	$I_F = 100\ \text{mA}$	$\Delta\lambda$		50		nm
Temp. Coefficient of $\lambda_p$	$I_F = 100\ \text{mA}$	$TK_{\lambda_p}$		0.2		nm/K
Rise Time	$I_F = 100\ \text{mA}$	$t_r$		800		ns
Rise Time	$I_F = 1.5\ \text{A}$	$t_r$		400		ns
Fall Time	$I_F = 100\ \text{mA}$	$t_f$		800		ns
Fall Time	$I_F = 1.5\ \text{A}$	$t_f$		400		ns

## Typical Characteristics ( $T_{amb} = 25^{\circ}\text{C}$ unless otherwise specified)

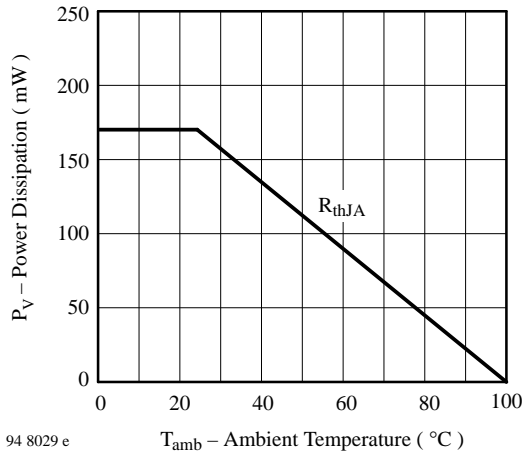


Figure 1 : Power Dissipation vs. Ambient Temperature

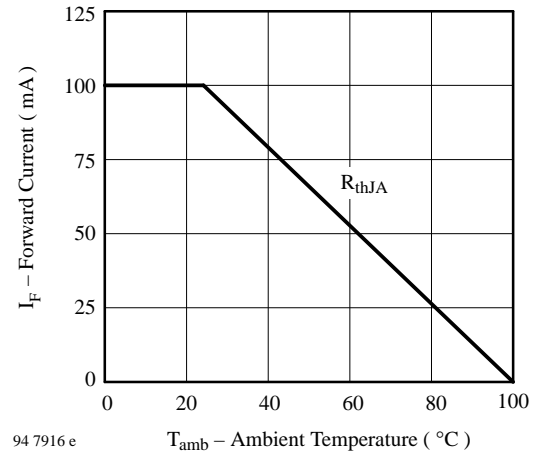


Figure 2 : Forward Current vs. Ambient Temperature

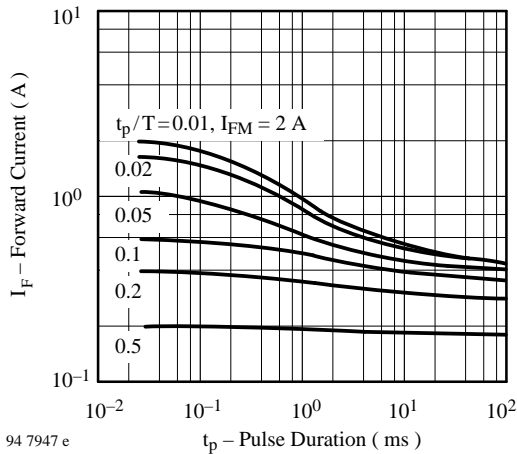


Figure 3 : Pulse Forward Current vs. Pulse Duration

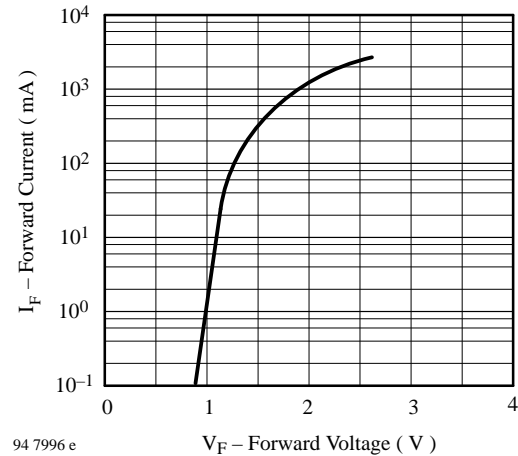


Figure 4 : Forward Current vs. Forward Voltage

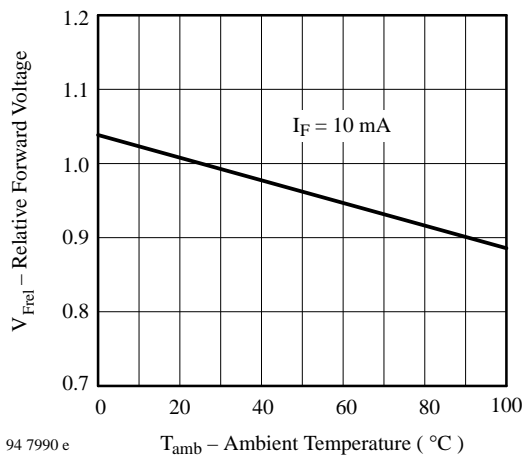


Figure 5 : Relative Forward Voltage vs. Ambient Temperature

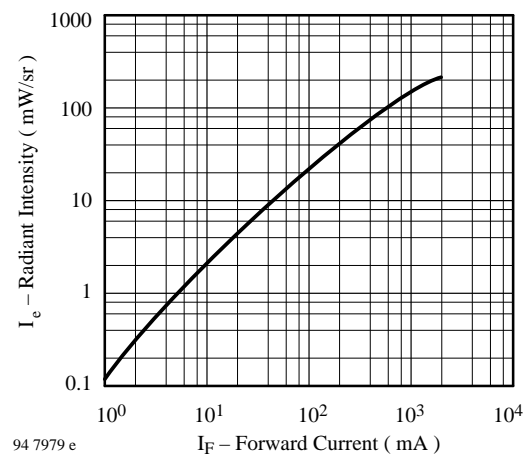


Figure 6 : Radiant Intensity vs. Forward Current

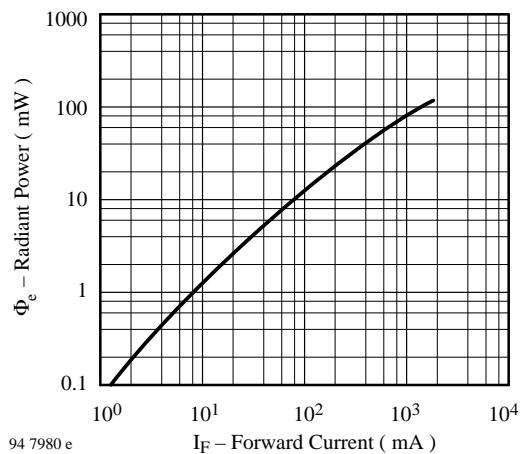


Figure 7 : Radiant Power vs. Forward Current

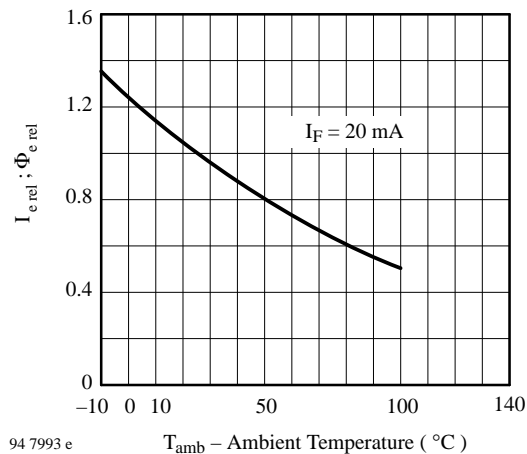


Figure 8 : Rel. Radiant Intensity/Power vs. Ambient Temperature

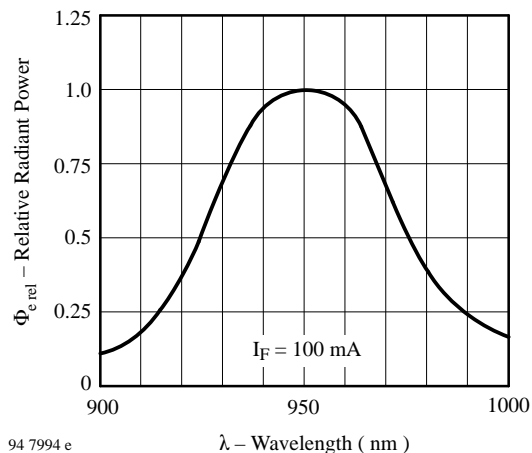


Figure 9 : Relative Radiant Power vs. Wavelength

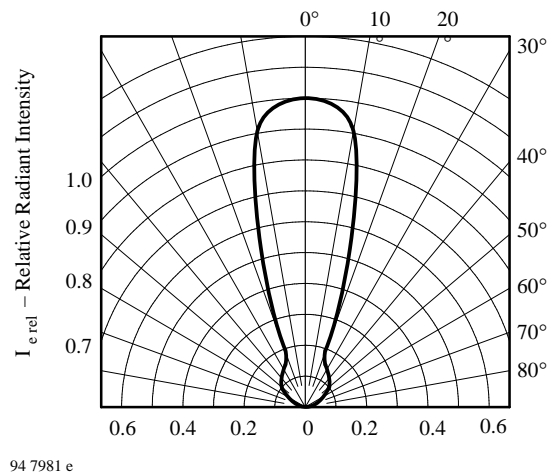
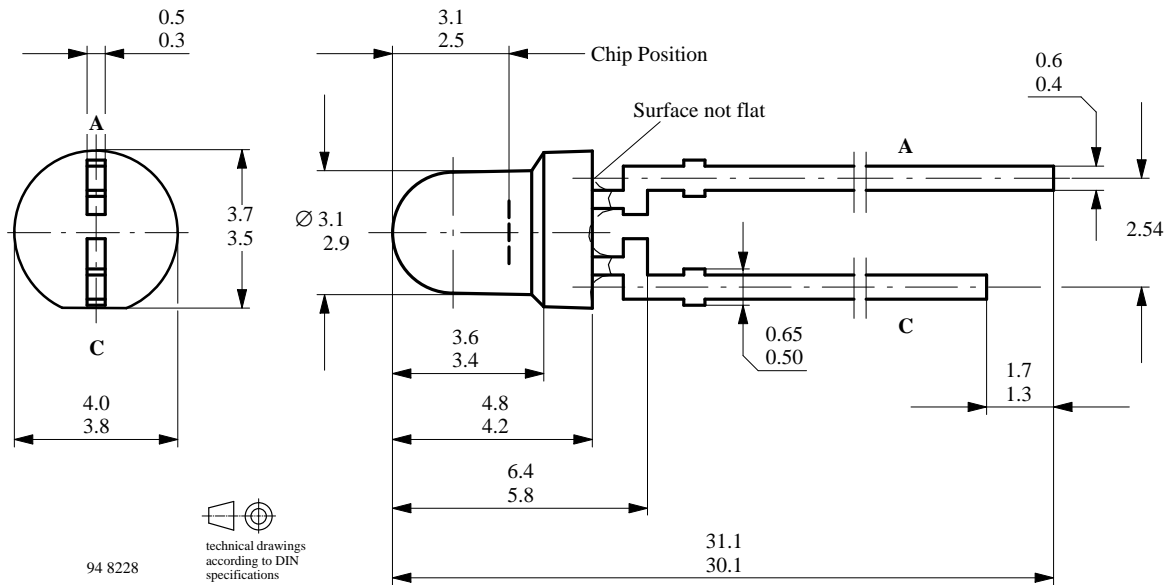


Figure 10 : Relative Radiant Intensity vs. Angular Displacement

## Dimensions in mm



**We reserve the right to make changes to improve technical design without further notice.**

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